



Thematic Network on Silicon on Insulator Technology, Devices and Circuits.  
[IST-1-506653-CA]

## EUROSOI "Who is Who" Guide

### *Name of the organisation*

<i>Organization Legal name:</i>	<b>S.O.I.TEC Silicon On Insulator Technologies</b>
<i>Organization short name:</i>	SOITEC
<i>Internet homepage:</i>	<b>www.soitec.com</b>

### *Contact person*

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### **Other Senior Researchers:** (up to 10 names, please include e-mail address)

Carlos Mazure ([carlos.mazure@soitec.fr](mailto:carlos.mazure@soitec.fr))  
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### **Experience and expertise fields:** (50 words)

Commercial spin-off of LETI, founded in March 1992 to produce very high-quality silicon-on-insulator (SOI) substrates. UNIBOND SOI wafers, introduced in July 1995, are manufactured using a patented technology called Smart Cut™. Process based on implantation technique and wafer bonding. Uses standard manufacturing equipment. 480 employees today. Annual turnover in the 80-100 MEuros range for the last fiscal years. SOITEC technology has been licensed to Shin Etsu Handotai and more recently to Siltronic for the manufacturing of SOI wafers.

### **Facilities and Equipment:**

Manufacturing / headquarters facility has been created in 1998 in Bernin, France, near Grenoble. The initial fab capacity has been increased (Bernin 2+R&D line) to a present level of more than 1,000,000 wafers start per year (equivalent eight-inch start wafers) and with an extension allowing 300mm capability. All equipments for Smart Cut SOI. See [www.soitec.com](http://www.soitec.com)

### **Three last international research projects:**

**MEDEA+ T206 : CMOS RF**